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Examiner : M. Dietrich
Art Unit : 2814
Docket No. : 52433/544

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: K. TATSUMI et al.

Serial No.: 09/254,118

Filed : May 19, 1999

For : METHOD OF PARTIALLY PLATING SUBSTRATE FOR ELECTRONIC DEVICES

Assistant Commissioner
for Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

Kindly amend the claims of the above-identified patent application as follows.

1-1. (Amended) A method of partially plating a substrate for electronic devices, comprising arranging small balls at selected portions of a substrate for mounting semiconductor devices thereon, [or a substrate for mounting electronic devices thereon and including a lead frame], and adhering or bonding the small balls thereto, and melting the small balls, thereby selectively plating the selected portions of the substrate for electronic devices with a different metal. *

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